



FIG. 17

SENSOR SUBSTRATE AND METHOD OF FABRICATING SAME

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Original Sheet

- 170 Form vias and anneal substrate
- 172 Fill vias and fire substrate
- 174 Screen print and fire conductors on electronics side of substrate
- 176 Pattern photoresist
- 178 Form metalization layer on electronics side of substrate
- 180 Deposit pillars on electronics side of substrate
- 182 Deposit alumina over electronics side of substrate
- 184 Remove pillars
- 186 Pattern photoresist
- 188 Form metalization layer on alumina
- 190 Pattern photoresist on sensing element side of substrate
- 192 Form metalization layer on sensing element side of substrate
- 194 Deposit caps over vias on sensing element side of substrate
- 196 Remove unwanted metal on both sides of the substrate

**FIG. 17**